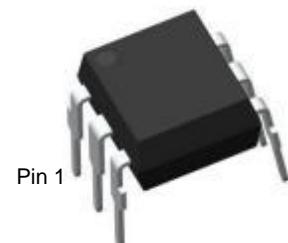




## Description

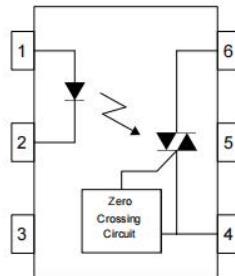
The HL3063 series of devices each consist of a GaAs infrared emitting diode optically coupled to a monolithic silicon zero voltage crossing photo triac. They are designed for use with a discrete power triac in the interface of logic systems, such as solid-state relays, industrial controls, motors, solenoids and consumer appliances.



Pin 1

## Features

- High input-output isolation voltage( $V_{ISO} = 5,000\text{Vrms}$ )
- High repetitive peak off-state voltage  $V_{DRM}$ .
- Min. 600V
- High critical rate of rise of off-state voltage(  $dv/dt$  : Min. 1000V/s )
- Operating Temperature:  $-40^{\circ}\text{C} \sim 110^{\circ}\text{C}$
- Safety approval
- (UL approved, VDE approved, CQC approved )
- RoHS



Pin Configuration  
1 Anode  
2 Cathode  
3 No Connection  
4 Terminal  
5 Substrate  
(do not connect)  
6 Terminal

## Applications

- Solenoid/valve controls
- Static power switch
- AC motor drivers
- Temperature Control

## Maximum Ratings

Parameter		Symbol	Values	Unit
Input	Forward Current	$I_F$	50	mA
	Reverse Voltage	$V_R$	6	V
	Power Dissipation	$P$	120	MW
	Junction Temperature	$T_J$	125	$^{\circ}\text{C}$
Output	Off-State Output Terminal Voltage	$V_{DRM}$	600	V
	Peak Repetitive Surge Current (PW=1ms 120 pps)	$I_{TSM}$	1	A
	On-State RMS Current	$I_{T(RMS)}$	100	mA
	Junction Temperature	$T_J$	125	$^{\circ}\text{C}$
	Collector Power Dissipation	$P_C$	150	mW
Operating temperature range		$T_{opr}$	40 ~ 110	$^{\circ}\text{C}$
Storage temperature range		$T_{stg}$	55 ~ 125	$^{\circ}\text{C}$
Total Power consumption		$P(W)$	250	mW
Isolation Voltage <sup>(1)</sup>		$V_{ISO}$	5000	Vrms

Notes:

(1). AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.  
(2). For 10 seconds



**Electronic Optical Characteristics (TA = 25°C)**

Parameter		Symbol	Min.	Typ.	Max.	Unit	Condition
Input	Forward Voltage	V <sub>F</sub>	-	1.2	1.4	V	I <sub>F</sub> =20mA
	Reverse Current	V <sub>R</sub>	-	-	5	μA	V <sub>R</sub> =6V
Output	Peak Blocking Current, Either Direction <sup>1</sup>	I <sub>DRM</sub>	-	-	500	nA	V <sub>DRM</sub> = Rated V <sub>DRM</sub>
	Peak On-State Voltage, Either Direction	V <sub>TM</sub>	-	-	3	V	I <sub>TM</sub> = 100mA Peak
	Critical rate of Rise of Off-State Voltage <sup>2</sup>	dv/dt	1000	-	-	V/μs	V <sub>in</sub> =240Vrms
Couple	Led Trigger Current, Current Required to Latch Output, Either Direction	I <sub>FT</sub>	-	-	15	mA	Main Terminal Voltage = 3V
			-	-	10		
			-	-	5		
	Holding Current, Either Direction	I <sub>H</sub>	-	400	-	μA	-
ZERO CROSSING	Inhibit Voltage	V <sub>INH</sub>	-	5	20	Volts	I <sub>F</sub> =Rated I <sub>FT</sub> , MT1- MT2 Voltage above which device will not trigger.
	Leakage in Inhibited State	I <sub>DRM2</sub>	-	-	500	μA	I <sub>F</sub> = Rated I <sub>FT</sub> , Rated V <sub>DRM</sub> , Off State

(1) Test voltage must be applied within dv/dt rating.

(2) This is static dv/dt. Commutating dv/dt is a function of the load-driving thyristor(s) only.



## Characteristics Curves

Fig.1 Forward current vs. Ambient temperature

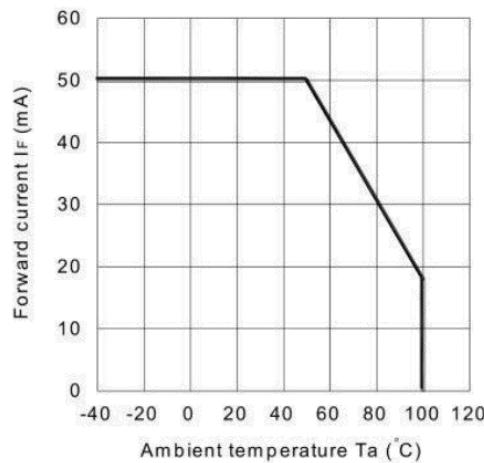


Fig.2 On-state current vs. Ambient temperature

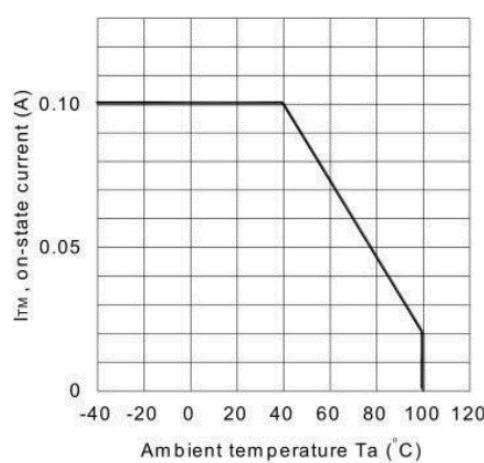


Fig.3 Minimum Trigger Current vs Ambient temperature

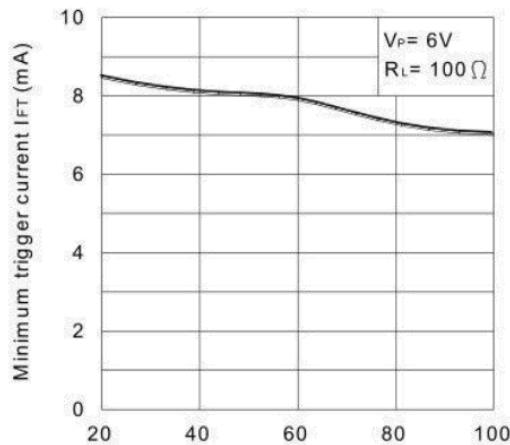


Fig.4 Forward current vs Forward Voltage

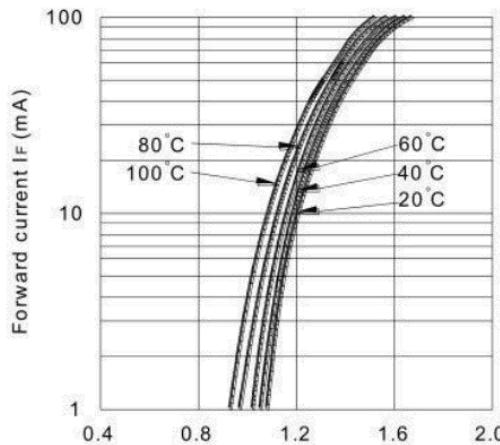


Fig.5 On-state voltage vs Ambient temperature

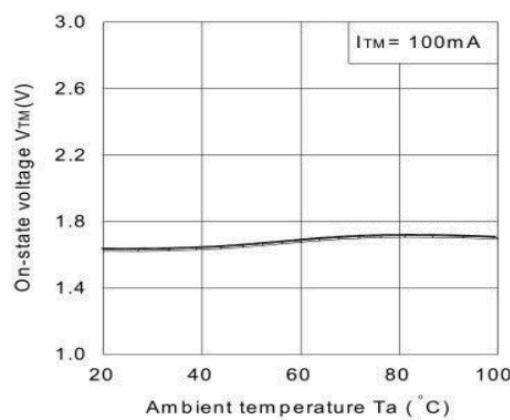


Fig.6 Holding current vs Ambient temperature

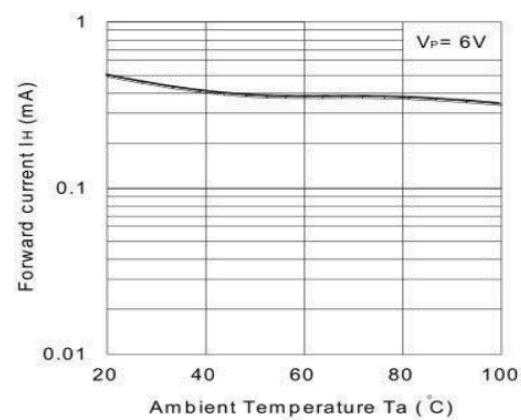




Fig.7 Repetitive peak off-state current vs Temperature

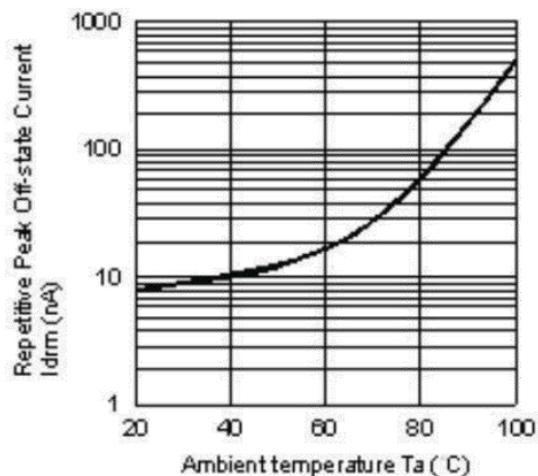


Fig.8 On-state current vs On-state voltage

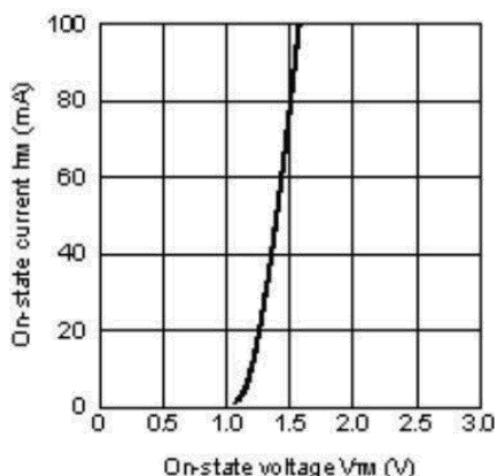


Fig.9 Basic Operation Circuit Medium/High Power Triac Drive Circuit

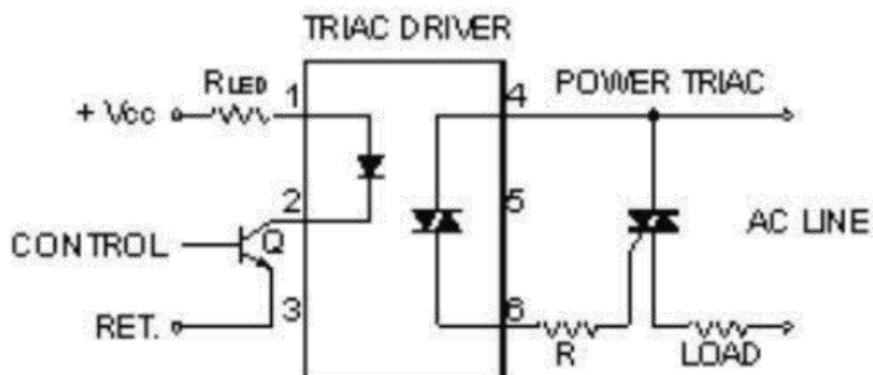
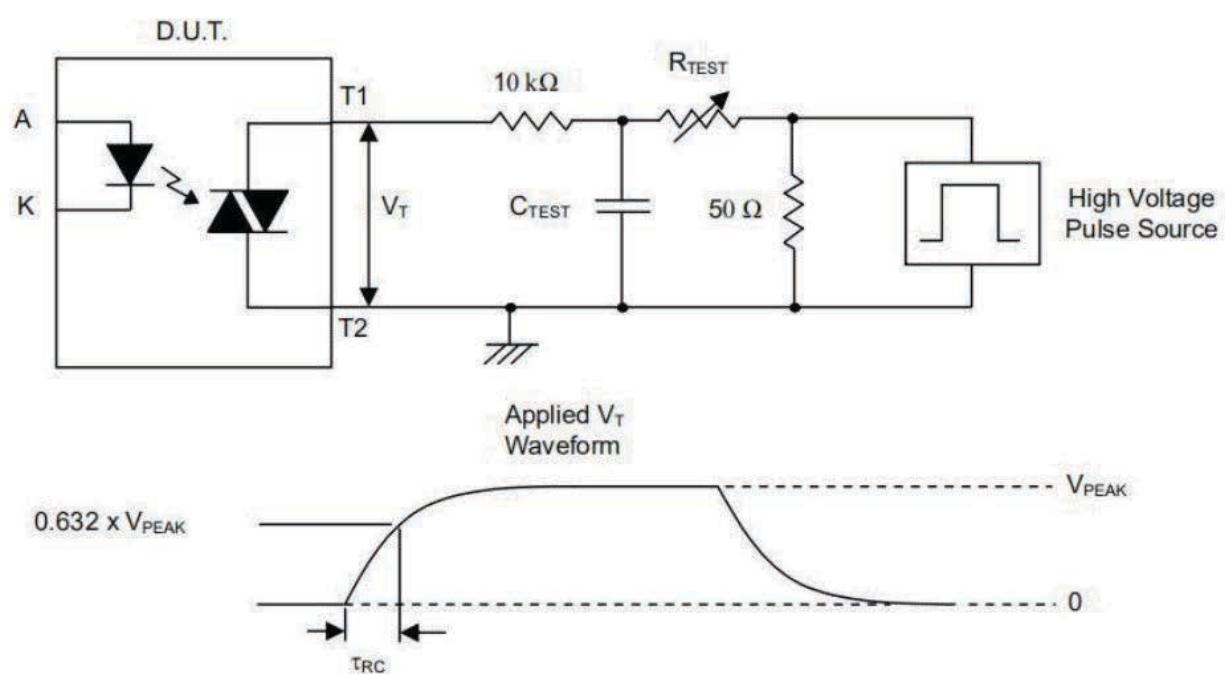


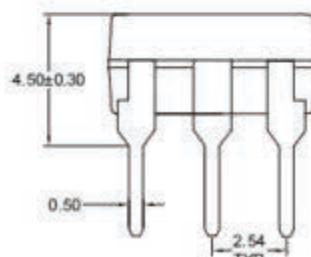
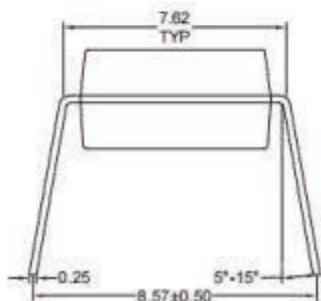
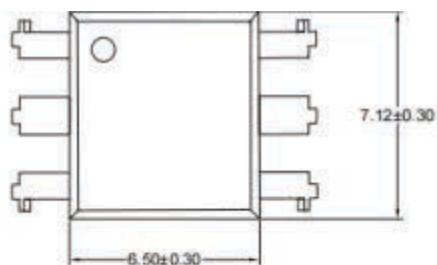
Fig.10.Static dv/dt Test Circuit & Waveform





## Outline Dimension

DIP-6 Type:



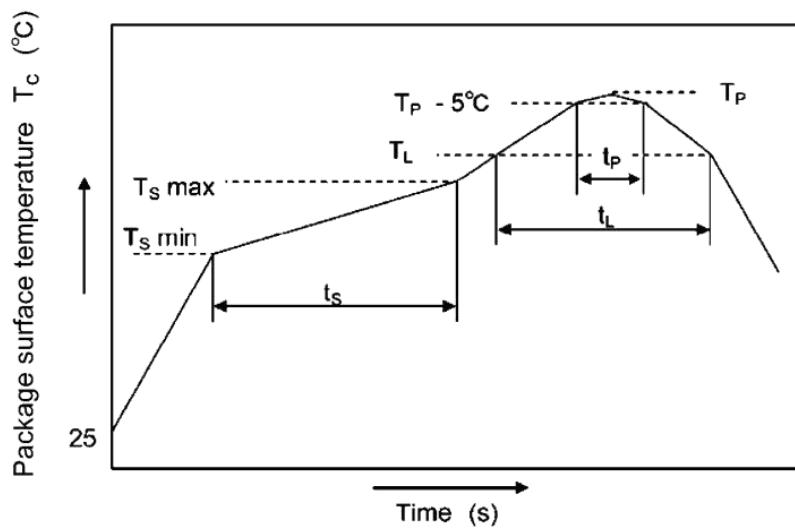


## Temperature Profile Of Soldering

### 1. IR Reflow soldering

(JEDEC-STD-020D compliant)

Profile item	Conditon
Preheat	
-Temperature Min (TSmin)	150°C
-Temperature Max (TSmax)	200°C
-Time (min to max) (ts)	90±30 sec
Soldering zone	
-Temperature (TL)	217°C
-Time (t <sub>L</sub> )	60-150 sec
Peak Temperature (TP)	260°C
-Time (TP-5°C to TP) (ts)	30 sec
Ramp-up rate	3°C / sec max
Ramp-down rate	3~6°C/ sec



### Notes:

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.



## 2. Wave soldering (JEDEC22A111 compliant)

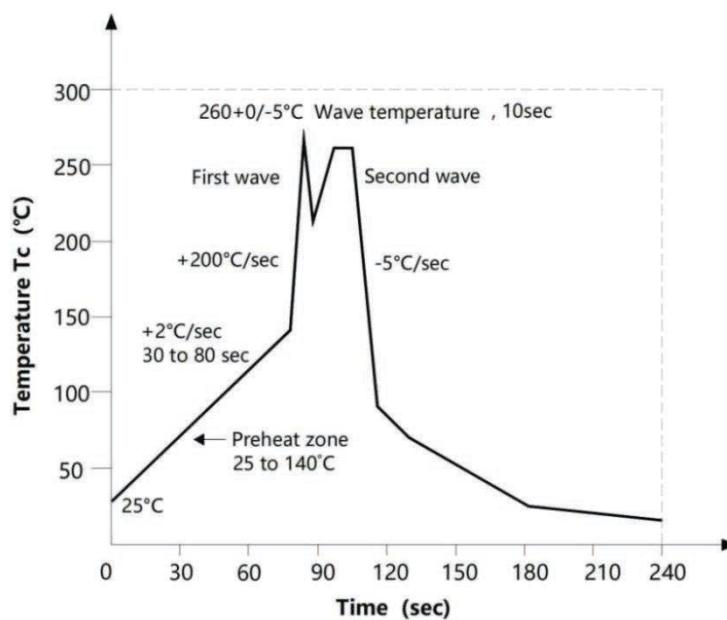
One time soldering is recommended within the condition.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature: 25 to 140°C.

Preheat time: 30 to 80 sec.



## 3. Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature: 380+0/-5°C

Time: 3 sec max.



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